

WEST

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L1: Entry 1 of 2

File: JPAB

Jul 31, 2002

PUB-NO: JP02002212773A

DOCUMENT-IDENTIFIER: JP 2002212773 A

TITLE: COPPER FOIL FOR PRINTED CIRCUIT BOARD AND METHOD FOR MANUFACTURING THE SAME

PUBN-DATE: July 31, 2002

INVENTOR-INFORMATION:

NAME	COUNTRY
MANABE, HISATOKU	

ASSIGNEE-INFORMATION:

NAME	COUNTRY
FUKUDA METAL FOIL & POWDER CO LTD	

APPL-NO: JP2001011153

APPL-DATE: January 19, 2001

INT-CL (IPC): C25 D 1/04; C22 C 19/00; C23 C 28/00; H05 K 3/00; H05 K 3/06; H05 K 3/24; H05 K 3/38

ABSTRACT:

PROBLEM TO BE SOLVED: To prepare a copper foil for a printed circuit board which is soluble in alkali etching and all other etching and has excellent chemical resistance and heat resistance.

SOLUTION: The copper foil for a printed circuit board has an alloy layer consisting of cobalt-nickel-tungsten at least on one side of the foil and further has a chromate film on the alloy layer depending on the case. The manufacturing method has a step for subjecting the copper foil to cathodic electrolysis in an electrolyte solution containing cobalt, nickel and tungsten to form the cobalt-nickel-tungsten layer and, as the case may be, a subsequent step for providing the chromate film on the layer containing hexavalent chromium.

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WEST**End of Result Set**

L1: Entry 2 of 2

File: DWPI

Jul 31, 2002

DERWENT-ACC-NO: 2003-032630

DERWENT-WEEK: 200303

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TITLE: Copper foil for high density printed circuit used in e.g. mobile telephone, has cobalt-nickel-tungsten alloy layer formed on one surface

PATENT-ASSIGNEE:

ASSIGNEE	CODE
FUKUDA KINZOKU HAKUFUN KOGYO KK	FKKI

PRIORITY-DATA: 2001JP-0011153 (January 19, 2001)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
<u>JP 2002212773 A</u>	July 31, 2002		009	C25D001/04

APPLICATION-DATA:

PUB-NO	APPL-DATE	APPL-NO	DESCRIPTOR
JP2002212773A	January 19, 2001	2001JP-0011153	

INT-CL (IPC): C22 C 19/00; C23 C 28/00; C25 D 1/04; H05 K 3/00; H05 K 3/06; H05 K 3/24; H05 K 3/38

ABSTRACTED-PUB-NO: JP2002212773A

BASIC-ABSTRACT:

NOVELTY - A cobalt-nickel-tungsten alloy layer is formed on one surface of a copper foil.

DETAILED DESCRIPTION - An INDEPENDENT CLAIM is included for the production of a copper foil.

USE - For high density printed circuits used in electric equipment such as mobile telephones and personal computers.

ADVANTAGE - A copper foil having a high chemical resistance and heat resistance is obtained.

CHOSEN-DRAWING: Dwg. 0/0

TITLE-TERMS: COPPER FOIL HIGH DENSITY PRINT CIRCUIT MOBILE TELEPHONE COBALT NICKEL TUNGSTEN ALLOY LAYER FORMING ONE SURFACE

DERWENT-CLASS: L03 M13 V04

CPI-CODES: L03-H04E3; M13-H;

EPI-CODES: V04-R02; V04-R03A; V04-R07P1;

=> s jp2002212773/pn
L2 1 JP2002212773/PN

=> d all

L2 ANSWER 1 OF 1 CAPLUS COPYRIGHT 2003 ACS on STN
AN 2002:568284 CAPLUS
DN 137:131253
TI Copper foil for printed circuit board and its production method
IN Manabe, Hisanori
PA Fukuda Metal Foil and Powder Co., Ltd., Japan
SO Jpn. Kokai Tokkyo Koho, 9 pp.
CODEN: JKXXAF
DT Patent
LA Japanese
IC ICM C25D001-04
ICS C22C019-00; C23C028-00; H05K003-00; H05K003-06; H05K003-24;
H05K003-38
CC 72-8 (Electrochemistry)
Section cross-reference(s): 56, 76
FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 2002212773	A2	20020731	JP 2001-11153	20010119 <--
PRAI	JP 2001-11153		20010119		

AB The invention relates to a Cu foil, suited for use in making a printed circuit board, wherein, at least, one of the Cu surfaces are coated with a Co-Ni-W alloy layer and optionally a chromate layer for enhancing the etchability, chem. and thermal resistances.

ST copper foil printed circuit board cobalt nickel tungsten alloy
IT Electrodeposition
Foils
Printed circuits
(copper foil for printed circuit board)

IT 444145-15-7 444145-16-8 444145-17-9 444145-18-0 444145-20-4
444145-21-5 444145-22-6 444145-23-7 444145-24-8 444145-25-9
444145-27-1 444145-28-2

RL: DEV (Device component use); USES (Uses)
(coating of; copper foil for printed circuit board)

IT 11104-59-9, Chromate 80507-95-5
RL: DEV (Device component use); USES (Uses)
(copper foil for printed circuit board)

IT 7440-50-8, Copper, uses
RL: DEV (Device component use); TEM (Technical or engineered material use); USES (Uses)
(copper foil for printed circuit board)

IT 6132-04-3P, Trisodium citrate dihydrate 10026-24-1P 10101-97-0P,
Nickel sulfate hexahydrate 11120-01-7P, Sodium tungstate
RL: PNU (Preparation, unclassified); TEM (Technical or engineered material use); PREP (Preparation); USES (Uses)
(in prepn. of coating layer; copper foil for printed circuit board)

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